

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10687713
<b>Filing Date:</b>	17-Oct-2003
<b>Title of Invention:</b>	Surface treated low-k dielectric as diffusion barrier for copper metallization
<b>First Named Inventor:</b>	Kuei-Wu Huang
<b>Filer:</b>	Richard A. Paikoff/Donna Winkler
<b>Attorney Docket Number:</b>	N1085-00184 [TSMC2002-132]

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>120</b>